Progress of the GRAIN Working group

Conveners: Lea Di Noto – Univ. and INFN Genova Alessandro Montanari- INFN Bologna

> SAND Technical meeting, Oct, 22th 2024







Overview

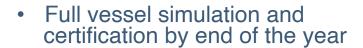
• This talk will cover the main progress in:

- Mechanics

- ASIC design

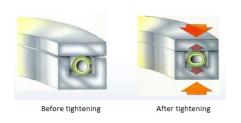
Inner Vessel

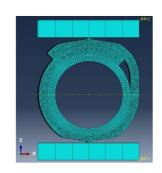
- Helicoflex simulation completed
 - Not reusable
 - Cost of 1 gasket ~ 5000 Euro

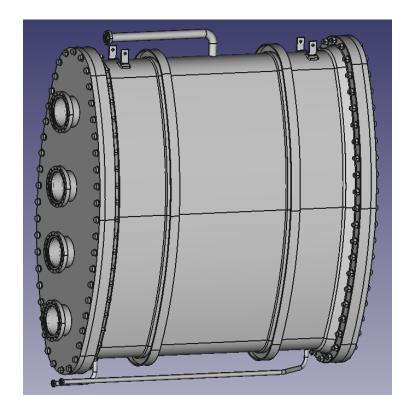




- Simic
- Mori Meccanica
- Cryoservice
- Tender: beginning of 2025



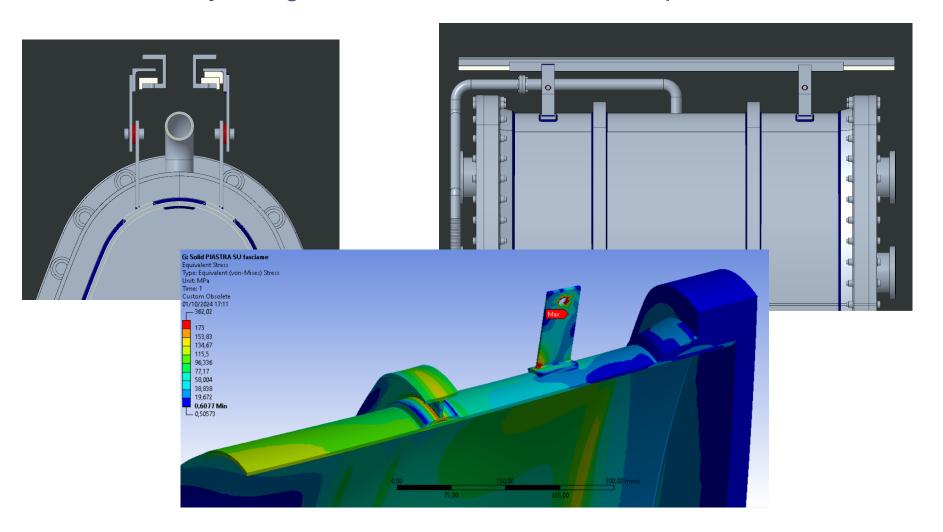






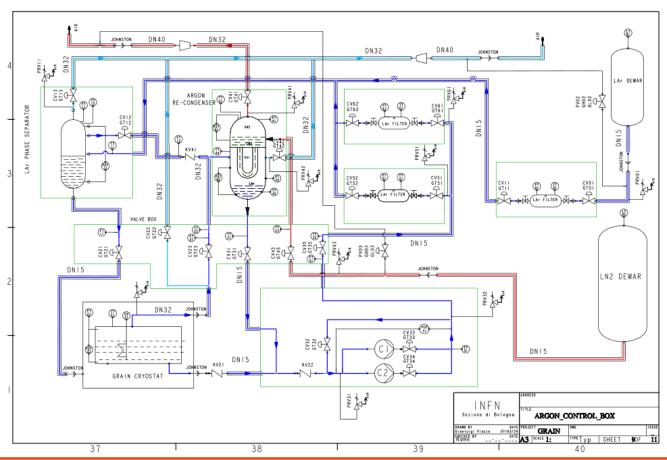
Sliding system

Preliminary design, to be used also in final experiment



Cryogenic System

- Draft design ready
- Met companies at BSBF- Trieste and Market Survey started:
 - Cryotec (IT), SIMIC (IT), DEMACO (NL)

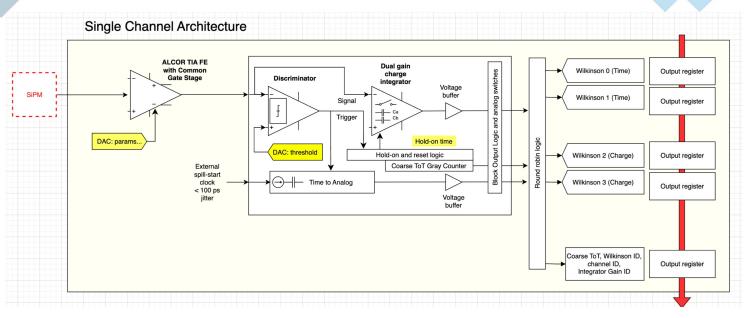






ASIC design

Proposed Pixel Readout Chain from this talk by To



Power consumption < 5 mW/ch

Architecture with 2 integrators for each channel

- For each integration window we record:
 - Time with O(100 ps) resolution for rising edge on a 0.5 pe threshold,
 - Time with O(2 ns) resolution for falling edge
 - Integrated charge



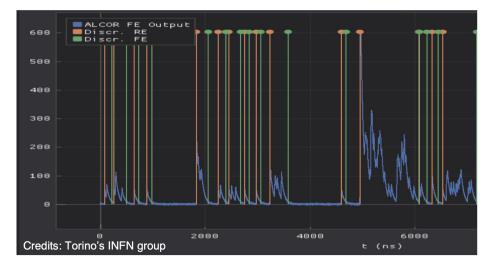
ASIC design validation

- Torino group developed a dedicated python code for simulating
 - single photon waveform
- electronics response



- ADC dead and conversion time
- dynamic range for each channel (maximum number of photons in each window)
- Front-End saturation (maximum number of photons piled up within 10-20 ns)

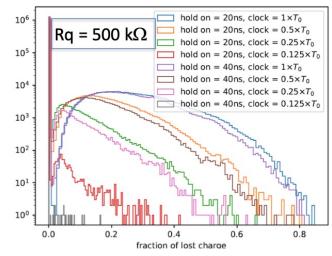
for different SiPM parameters (quenching resistor, SiPM size, ..)



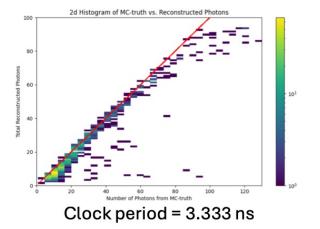
ASIC validation: first conclusions

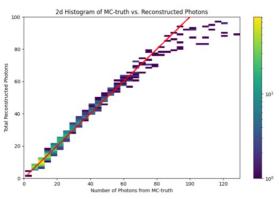
- Parameters under validation:
 - ADC dead and conversion time
- → we need a faster ADC (x4)

with coded mask



with lenses





1/4 Clock period = 0.833 ns

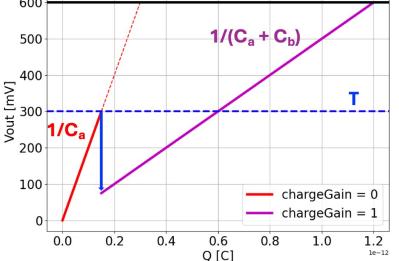


From here

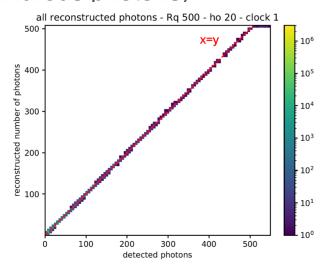
ASIC validation: first conclusions

- Parameters under validation:
 - Dynamic range for each channel

600 $1/(C_a + C_b)$ 500 400



→two gains for integrators (up to few hundreds photons)



- Front-End saturation (maximum number of photons piled-up within 10-20 ns)
 - to be investigated soon

ASIC design: current activities

Ongoing Activities: Pixel Design

S. Durando

Integrator Design:

- Transistor level design in Virtuoso
 - Current mirror based
 - DC current compensation
 - Two gains
- First simulation analyses soon

ADC Design Improvements:

- Backward compatibility
- New SAR-based conversion algorithm
 - Faster conversion
 - · Control logic and current injection improvements
- Block ready for integration expected by the beginning of December

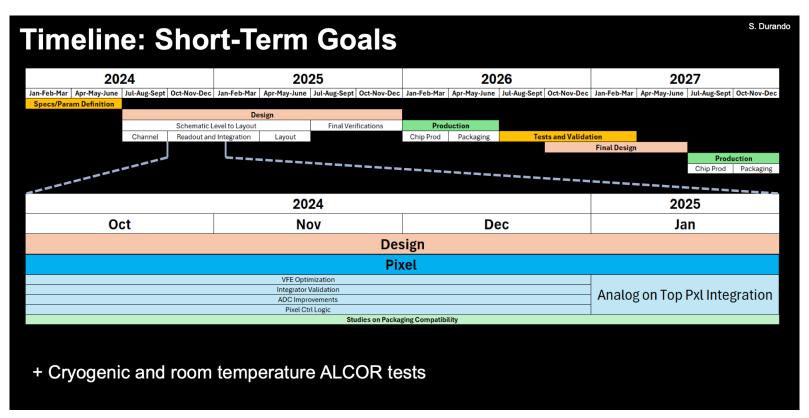
VFE Optimization:

- ALCOR Cryogenic tests and simulations showed:
 - Vth and R variations impact mostly the TIA and the DACs
- Optimization
 - TIA and DACs design optimization
 - Configurable resistor arrays and current correction

Pixel



ASIC design: timeline



- By ≈ April : 2 x 2 Pixels Matrix Prototype
 - No real production
 - Case study for optimizing the full integration flow



Detector readout design

TASK	Design	Test
Test Mock up	Bologna	
ASIC	Torino	
SiPM characterization	-	NOA?
ASIC Test Board	To/Ge/Bo	
ASIC Test Daq	To/Ge/Bo	
GCB_L	Ge/Bo	
GCB_M	Bo/Ge	
GCIB+connectivity	Bologna	Ge
SiPM calib in GRAIN		
GWIB Hardware	Genova	Во
GWIB Analog mezz.	Bologna	Ge
GWIB Firmware	Genova	Во
Power+bias	Genova	Во
Timing master IT	Bologna	
DUNE DAQ in IT	Genova	

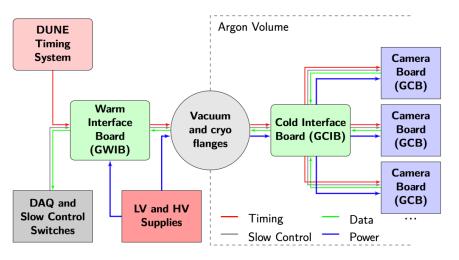
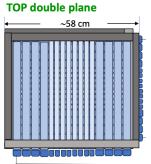


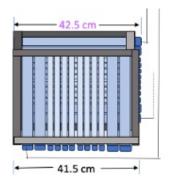
Figure 1.5: Block diagram of the GRAIN electronic system.

After the meeting on 16-10-2024 among GE and BO groups

CRT for ARTIC installed at Ge!







DEL SALENTO

CRT GOALS:

- · Trigger for the LAr acquisition (fourfold coincidence)
- · Two-view tracking to help the LAr event reconstruction



Trigger condition: Fourfold coincidence



Conclusions

Many important activities are in progress:

- Mechanical design for vessels
- Cryogenics design and refurbishing in Legnaro
- ASIC design with Torino group
- Test with prototypes
 - → finally started
 - → CRT installed

Tests of prototypes in ARTIC

Mechanics completed





